



SPECIFICATION

- · Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor
- · Samsung P/N :
- CL31B475KBHNNNE

(Reference sheet)

| | - | |
|---|-------------|---|
| • | Description | : |

CAP, 4.7uF, 50V, ±10%, X7R, 1206

A. Samsung Part Number

| | | <u>CL</u> ① | <u>31</u> ② | <u>B</u> 3 | <u>475</u> ④ | <u>K</u> 5 | <u>B</u> 6 | <u>Н</u> 7 | <u>N</u> 8 | <u>N</u> 9 | <u>N</u> 10 | <u>Е</u> Ш | |
|---|---------------|---------------------------------------|----------------|---------------|-----------------|---------------|---------------|---------------|---------------|---------------|----------------|---------------|---------------|
| 1 | Series | Samsung Multi-layer Ceramic Capacitor | | | | | | | | | | | |
| 2 | Size | 1206 (inch c | ode) | | L: | 3.20 | ± 0.20 | mm | | | W: | 1.60 ± 0.20 | mm |
| 3 | Dielectric | X7R | | | | 8 | Inner | elect | rode | | | Ni | |
| 4 | Capacitance | 4.7 uF | | | | | Term | inatio | on | | | Cu | |
| 5 | Capacitance | ±10 % | | | | | Platir | ng | | | | Sn 100% | (Pb Free) |
| | tolerance | | | | | 9 | Prod | uct | | | | Normal | |
| 6 | Rated Voltage | 50 V | | | | 10 | Spec | ial | | | | Reserved fo | r future use |
| 1 | Thickness | 1.60 ± 0.20 mm | | | | 1 | Pack | aging | I | | | Embossed T | Type, 7" reel |

B. Structure & Dimension



| Samsung P/N | Dimension(mm) | | | | | | | | |
|-----------------|---------------|-------------|-------------|-------------|--|--|--|--|--|
| Samsung F/N | L | W | Т | BW | | | | | |
| CL31B475KBHNNNE | 3.20 ± 0.20 | 1.60 ± 0.20 | 1.60 ± 0.20 | 0.50 ± 0.30 | | | | | |

C. Samsung Reliablility Test and Judgement Condition

| | Judgement | Test condition | | | |
|-------------------|--|---|--|--|--|
| Capacitance | Within specified tolerance | 1 ^{kHz} ±10% / 1.0±0.2Vrms | | | |
| Tan δ (DF) | 0.1 max. | *A capacitor prior to measuring the capacitance is heat treated at $150^{\circ}C$ +0/- $10^{\circ}C$ for 1 hour and maintained in ambient air for 24±2 hours. | | | |
| Insulation | 10,000Mohm or 100Mohm× <i>μ</i> F | Rated Voltage 60~120 sec. | | | |
| Resistance | Whichever is smaller | | | | |
| Appearance | No abnormal exterior appearance | Microscope (×10) | | | |
| Withstanding | No dielectric breakdown or | 250% of the rated voltage | | | |
| Voltage | mechanical breakdown | | | | |
| Temperature | X7R | | | | |
| Characteristics | (From-55℃ to 125℃, Capacitance change | should be within ±15%) | | | |
| Adhesive Strength | No peeling shall be occur on the | 500g·f, for 10±1 sec. | | | |
| of Termination | terminal electrode | | | | |
| Bending Strength | Capacitance change : within ±12.5% | Bending to the limit (1mm) | | | |
| | | with 1.0mm/sec. | | | |
| Solderability | More than 75% of terminal surface | SnAg3.0Cu0.5 solder | | | |
| _ | is to be soldered newly | 245±5℃, 3±0.3sec. | | | |
| | | (preheating : 80~120°C for 10~30sec.) | | | |
| Resistance to | Capacitance change : within ±7.5% | Solder pot : 270±5°C, 10±1sec. | | | |
| Soldering Heat | Tan δ, IR : initial spec. | | | | |
| Vibration Test | Capacitance change : within $\pm 5\%$ Tan δ , IR : initial spec. | Amplitude : 1.5mm From 10Hz to 55Hz (return : 1min.) 2hours × 3 direction (x, y, z) | | | |
| Moisture | Capacitance change : within ±12.5% | With rated voltage | | | |
| Resistance | Tan δ : 0.125 max | 40±2℃, 90~95%RH, 500+12/-0hrs | | | |
| | IR : 500Mohm or 12.5Mohm × μ F | | | | |
| | Whichever is smaller | | | | |
| High Temperature | Capacitance change : within ±12.5% | With 150% of the rated voltage | | | |
| Resistance | Tan δ : 0.125 max | Max. operating temperature | | | |
| | IR : 1,000Mohm or 25Mohm × μF | 1,000+48/-0hrs | | | |
| | Whichever is smaller | | | | |
| Temperature | Capacitance change : within ±7.5% | 1 cycle condition | | | |
| Cycling | Tan δ, IR : initial spec. | Min. operating temperature $\rightarrow 25^{\circ}$ C | | | |
| | | \rightarrow Max. operating temperature \rightarrow 25°C | | | |
| | | | | | |
| | | 5 cycle test | | | |
| | - | | | | |

st The reliability test condition can be replaced by the corresponding accelerated test condition.

D. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260±5°C, 30sec.)

A Product specifications included in the specifications are effective as of March 1, 2013. Please be advised that they are standard product specifications for reference only.

We may change, modify or discontinue the product specifications without notice at any time.

So, you need to approve the product specifications before placing an order.

Should you have any question regarding the product specifications,

please contact our sales personnel or application engineers.

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The products listed in this Specification sheet are **NOT** designed and manufactured for any use and applications set forth below.

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If you have any questions regarding this 'Limitation of Use and Application', you should first contact our sales personnel or application engineers.

- *①* Aerospace/Aviation equipment
- 2 Automotive or Transportation equipment (vehicles, trains, ships, etc)
- 3 Medical equipment
- (4) Military equipment
- 5 Disaster prevention/crime prevention equipment
- Ø Power plant control equipment
- ⑦ Atomic energy-related equipment
- Indersea equipment
- Itraffic signal equipment
- Data-processing equipment
- ① Electric heating apparatus, burning equipment
- ② Safety equipment
- 13 Any other applications with the same as or similar complexity or reliability to the applications